

Vacuum Electronics

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(Eds.)

Vacuum Electronics

Components and Devices

With 388 Figures

 Springer

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Library of Congress Control Number: 2007934267

ISBN 978-3-540-71928-1 Springer Berlin Heidelberg New York

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Typesetting: Data prepared by Vtex using a Springer LaTeX macro package
Cover design: WMXDesign GmbH, Heidelberg

Printed on acid-free paper SPIN 10934111 57/3180/vtex 5 4 3 2 1 0

Preface

In 1989 the “Handbuch der Vakuumelektronik” (Handbook of Vacuum Electronics) was published in the R. Oldenbourg Verlag, München, Wien, edited by J. Eichmeier and H. Heynisch. During the past 18 years considerable progress has been achieved in the fields of vacuum electronic components, systems and procedures. In the present book a group of 36 well-known experts from industry, scientific institutes and universities report about the fundamentals, state-of-the-art, recent developments and their own experiences in all important areas of Vacuum Electronics.

The operation of vacuum electronic components and devices is based on the motion of electrons or ions under the influence of electric, magnetic or electromagnetic fields. Presently, research activities are concentrated on microwave tubes, especially travelling wave tubes, klystrons, gyrotrons and cross-field devices; switching tubes and vacuum relays; photomultipliers, image converter and image amplifier tubes; vacuum and plasma panel displays; electron and ion beam systems; particle accelerators; electron and ion microscopes; ion and plasma propulsion systems; light sources and gas lasers; X-ray tubes; gas discharge systems; vacuum electronic systems for semiconductor technology; and finally, vacuum technology and vacuum measuring techniques.

Vacuum electronic components, systems and procedures are applied in information, measuring and control engineering and also in high frequency, nuclear, plasma and biomedical engineering. This book presents the current state-of-the-art of vacuum electronics in research, development and production. Its reader should have a basic knowledge of electronics, especially the principles of vacuum electronics. It may be a useful source of proper information for students of electrical engineering and physics and also for engineers and physicists who develop or apply vacuum electronic components and devices in a variety of technological fields. The literature cited is the most appropriate for further reading. All the chapters begin with a historical note, and the references credit the scientists and engineers who were responsible for major breakthroughs and advancements in the various fields of vacuum electronics.

On behalf of all co-authors, the editors thank Springer-Verlag, Berlin, Heidelberg, New York, for the careful lay-out and printing of this book. The editors thank all co-authors for their excellent contributions.

Munich, Karlsruhe
January 2008

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Contents

| | |
|--|----------|
| List of Contributors | xv |
| 1 Microwave Tubes | 1 |
| <i>G. Faillon, G. Kornfeld, E. Bosch, and M.K. Thumm</i> | 1 |
| 1.1 Introduction | 1 |
| 1.1.1 Review of State-of-the-Art and Present Situation | 1 |
| 1.1.2 Historical Development | 1 |
| 1.1.3 Basic Operating Principles and Definitions | 4 |
| 1.2 Klystrons | 12 |
| 1.2.1 Klystron Amplifiers | 12 |
| 1.2.2 Multibeam Klystrons | 20 |
| 1.2.3 Inductive Output Tubes (IOT) | 22 |
| 1.3 Traveling Wave Tube (TWT) | 24 |
| 1.3.1 Introduction | 24 |
| 1.3.2 TWT Design and Operation Principle | 25 |
| 1.3.3 TWT Physics | 29 |
| 1.3.4 TWT Applications | 45 |
| 1.4 Extended Interaction Klystron EIK | 50 |
| 1.4.1 Introduction | 50 |
| 1.4.2 Extended Interaction Circuit Design | 50 |
| 1.4.3 Typical Performance and Applications | 50 |
| 1.5 Backward Wave Oscillator (BWO) | 52 |
| 1.5.1 Introduction | 52 |
| 1.5.2 BWO Operation Principle | 52 |
| 1.5.3 BWO Applications | 54 |

| | | |
|----------|---|-----------|
| 1.6 | Magnetrons and Cross-Field Amplifiers | 55 |
| 1.6.1 | Magnetrons | 55 |
| 1.6.2 | Cross-Field Amplifiers (CFA) | 58 |
| 1.6.3 | Cross-Field Backward Wave Oscillator (MBWO) | 60 |
| 1.7 | Fast-Wave Devices | 61 |
| 1.7.1 | Interaction Principles | 63 |
| 1.7.2 | Dispersion Diagrams of Fast-Wave Interactions | 65 |
| 1.7.3 | Gyrottron Oscillator | 70 |
| 1.7.4 | Gyro-Amplifiers | 74 |
| 1.7.5 | Gyro-BWO | 78 |
| 1.7.6 | Free-Electron Maser (FEM) | 78 |
| 1.8 | Future Trends and Applications | 80 |
| | References | 82 |
| 2 | Vacuum Displays | 85 |
| | <i>K. Blankenbach, G. Gassler, and H.W.P. Koops</i> | 85 |
| 2.1 | Introduction | 85 |
| 2.1.1 | Historical Development | 85 |
| 2.1.2 | Overview | 87 |
| 2.1.3 | Fundamentals of Displays | 89 |
| 2.1.4 | Fundamentals of Display Parameters | 93 |
| 2.1.5 | Comparison of Various Display Technologies | 99 |
| 2.2 | Cathode Ray Tubes (CRT) | 99 |
| 2.2.1 | Historical Development | 100 |
| 2.2.2 | Electrophysical Fundamentals | 101 |
| 2.2.3 | Present State-of-the-Art | 107 |
| 2.2.4 | Future Aspects | 111 |
| 2.3 | Plasma Panel Displays (PDP) | 111 |
| 2.3.1 | Historical Development | 112 |
| 2.3.2 | Electrophysical Fundamentals | 112 |
| 2.3.3 | Present State-of-the-Art and Applications | 115 |
| 2.3.4 | Future Aspects | 117 |
| 2.4 | Vacuum Fluorescent Displays (VFD) | 117 |
| 2.4.1 | Historical Development | 118 |
| 2.4.2 | Electrophysical Fundamentals | 118 |
| 2.4.3 | Present State-of-the-Art and Applications | 119 |
| 2.4.4 | Future Aspects | 122 |
| 2.5 | Field Electron Displays (FED) | 122 |
| 2.5.1 | Historical Development | 122 |
| 2.5.2 | Electrophysical Fundamentals | 122 |
| 2.5.3 | Present State-of-the-Art and Applications | 123 |
| 2.5.4 | Future Aspects | 124 |
| | References | 125 |

3 Radiation Sensitive Vacuum Electronic Components and Devices 127
J.A. Eichmeier 127
 3.1 Historical Development 127
 3.2 Electrophysical Fundamentals 128
 3.2.1 Photoelectron Emission 128
 3.2.2 Secondary Electron Emission 130
 3.2.3 Electron Optics 131
 3.3 Present State-of-the-Art and Applications 132
 3.3.1 Secondary Electron Multipliers 132
 3.3.2 Image Converters and Image Amplifiers 139
 3.3.3 Television Camera Tubes 143
 3.4 Future Aspects of Radiation Sensitive Vacuum Electronic Components . . . 153
 References 154

4 Electron Beam Devices for Materials Processing and Analysis 155
H. Bluhm, B. Han, A.G. Chmielewski, D. von Döbeneck, U. Gohs, J. Gstöttner, G. Mattausch, H. Morgner, H.W.P. Koops, A. Reichmann, O. Röder, S.W. Schulz, B. Wenzel, and O. Zywitzki 155
 4.1 Introduction and History 155
 4.1.1 Electron Optics 157
 4.1.2 Electron Sources 164
 4.2 Thermal Materials Processing 171
 4.2.1 Welding 173
 4.2.2 Thermal Surface Modification 178
 4.2.3 High-rate Evaporation by Electron Beam Guns 181
 4.2.4 Electron Beam Melting and Refining in Vacuum Metallurgy 184
 4.3 Non-Thermal Processing Techniques 189
 4.3.1 Survey of Chemical Effects Caused by Electron Beams 189
 4.3.2 Electron-beam Lithography 191
 4.3.3 Electron Beam-induced Processing 195
 4.3.4 Curing of Organic Coatings and Surface Layers 198
 4.3.5 Refinement of Polymer Materials 201
 4.3.6 Control of Pathogens 202
 4.3.7 Flue Gas and Wastewater Treatment 205
 4.4 Materials Analysis, Imaging and Testing 206
 4.4.1 Scanning Electron Microscopy 206
 4.4.2 Electron Microscopy 209
 4.4.3 Electron Beam Spectroscopy and Analysis 218
 4.4.4 Electron Beam Testing 219
 References 224

5 Ion Beam Devices for Material Processing and Analysis 231
F. Rüdénauer, H.W.P. Koops, G. Hobler, L. Palmetshofer, and H. Bluhm 231
 5.1 Ion Beam Analysis 231

- 5.1.1 Historical Development 231
- 5.1.2 Electrophysical Fundamentals 232
- 5.1.3 Analysis Techniques 232
- 5.2 Ion Beam Materials Modification and Mask Repair 236
 - 5.2.1 Historical Development 236
 - 5.2.2 Electrophysical Fundamentals 237
 - 5.2.3 Present State-of-the-Art and Applications 238
 - 5.2.4 Future Aspects 245
- 5.3 Ion Implantation 245
 - 5.3.1 Historical Development 245
 - 5.3.2 Electrophysical Fundamentals 247
 - 5.3.3 Present State-of-the-Art and Applications 248
 - 5.3.4 Future Aspects 253
- 5.4 High Power Ion Beams 253
 - 5.4.1 Historical Development 253
 - 5.4.2 Introduction 254
 - 5.4.3 Accelerator Physics 254
 - 5.4.4 Beam Transport 259
 - References 259

- 6 Ion Propulsion Systems 265**
H. Bassner, R. Killinger, J. Mitterauer, F. Rüdener, N. Koch, and G. Kornfeld 265
- 6.1 Electrostatic Ion Thrusters and RF-Ion Thruster RIT 265
 - 6.1.1 Introduction 265
 - 6.1.2 Historical Development of RIT 266
 - 6.1.3 Electrophysical Fundamentals 266
 - 6.1.4 Present State-of-the-Art and Applications of RIT 267
 - 6.1.5 Applications of RIT Thrusters 268
 - 6.1.6 Future Aspects 271
- 6.2 Field Emission Electric Propulsion (FEEP) 272
 - 6.2.1 Historical Development 272
 - 6.2.2 Electrophysical Fundamentals 273
 - 6.2.3 Present State-of-the-Art and Applications 274
 - 6.2.4 Future Aspects 276
- 6.3 Hall Effect Thrusters 278
 - 6.3.1 Introduction 278
 - 6.3.2 Operational Concept and Characteristics 279
 - 6.3.3 Examples for HET Applications in Space Missions 285
- 6.4 High Efficiency Multistage Plasma Thruster 288
 - 6.4.1 Introduction 288
 - 6.4.2 Design and Physical Operation Principle 289
 - 6.4.3 Design and Performance 293
 - 6.4.4 Future Developments and Potential Applications 296
 - References 297

7 Infrared, Light, Ultraviolet, Laser- and X-ray-Tubes 303
A. Ulrich, M. Born, H.W.P. Koops, H. Bluhm, and T. Jüstel 265

7.1 General Physics of Photon Generation 303
 7.1.1 Historical Development 303

7.2 Laser 307
 7.2.1 Introduction 307
 7.2.2 Specific Laser Devices 308
 7.2.3 Ion Lasers 310
 7.2.4 Excimer Lasers 311
 7.2.5 Electron Beam Pumping of High Power KrF-laser 313

7.3 Smith–Purcell Effect 315
 7.3.1 Historical Development 315
 7.3.2 Electrophysical Fundamentals 315
 7.3.3 Present State 316
 7.3.4 Future Aspects for THz Sources 317

7.4 Millimetre and Infrared Light Sources 317
 7.4.1 Historical Development 317
 7.4.2 Generation of IR Radiation 318
 7.4.3 IR Applications 318
 7.4.4 Generation of THz Radiation 319
 7.4.5 THz Applications 319
 7.4.6 Further Developments 321
 7.4.7 Detection of THz Radiation 322

7.5 Visible Light Sources 322
 7.5.1 History and Introduction 322
 7.5.2 Incandescent Lamps 323
 7.5.3 Gas Discharge Lamps 324
 7.5.4 Fluorescent Coatings 326
 7.5.5 High-Pressure Discharge Lamps 329
 7.5.6 General Light Source Survey 334

7.6 Ultraviolet Light Sources 334
 7.6.1 Introduction 334
 7.6.2 Thermal Tungsten Lamps for Intensity Calibration 335
 7.6.3 Deuterium Lamps 335
 7.6.4 UV Arc Lamps 336
 7.6.5 Mercury Lamps 337
 7.6.6 Hollow Cathode Lamps 338
 7.6.7 Excimer Light Sources 338
 7.6.8 Excimer Lamps Using Discharge Excitation Glow Discharges 340
 7.6.9 Excimer Lamps Using Electron Beam Excitation 342

7.7 X-ray-Tubes 343
 7.7.1 History and Generation of X-rays 343
 7.7.2 Generation of X-rays 343
 7.7.3 X-ray Filters 344
 7.7.4 X-ray Dosimetry 345

| | |
|---|------------|
| 7.7.5 X-ray Tubes | 346 |
| 7.7.6 Synchrotrons | 348 |
| 7.7.7 X-ray Detection | 349 |
| 7.7.8 Applications | 349 |
| 7.7.9 Future Developments: Miniaturized X-ray Tubes | 350 |
| References | 350 |
| 8 Particle Accelerators | 355 |
| <i>M. Seidel and K. Zapfe</i> | <i>355</i> |
| 8.1 History and Types of Accelerators | 357 |
| 8.1.1 Static Accelerators | 357 |
| 8.1.2 Circular Resonant Acceleration | 358 |
| 8.1.3 Linear Resonant Acceleration | 361 |
| 8.1.4 Acceleration by Induction (Betatron) | 363 |
| 8.1.5 Particle Sources | 364 |
| 8.1.6 Colliders | 365 |
| 8.1.7 Synchrotron Radiation Sources | 368 |
| 8.2 Essentials of Beam Dynamics | 369 |
| 8.2.1 Beam Emittance and Phase Space | 369 |
| 8.2.2 Equations of Motion and Strong Focusing | 372 |
| 8.2.3 Synchrotron Radiation | 376 |
| 8.3 Vacuum Requirements in Particle Accelerators | 379 |
| 8.3.1 Beam Gas Interaction | 379 |
| 8.3.2 Static and Dynamic Aspects of Accelerator Vacuum Systems | 383 |
| 8.4 Layout of Accelerator Vacuum Systems | 386 |
| 8.4.1 Pressure Profile Calculations for One-dimensional Systems | 387 |
| 8.4.2 Pumping | 389 |
| 8.4.3 Instrumentation | 393 |
| 8.4.4 Material Selection and Design Implications | 394 |
| 8.4.5 Cleaning and Treatment of Vacuum Chambers | 397 |
| 8.5 Special Topics of Particle Accelerator Vacuum Systems | 398 |
| 8.5.1 Accelerators with Cold Bore Vacuum Systems | 398 |
| 8.5.2 Synchrotron Radiation Facilities | 401 |
| 8.5.3 Particle Free UHV-Systems | 402 |
| References | 404 |
| 9 Vacuum Interrupters | 407 |
| <i>R. Renz</i> | <i>407</i> |
| 9.1 Historical Development | 407 |
| 9.2 Physical Fundamentals | 409 |
| 9.2.1 Interrupting Capability | 409 |
| 9.2.2 Dielectric Properties | 414 |
| 9.2.3 Current-Zero Effects | 416 |
| 9.2.4 Mechanical and Thermal Aspects | 416 |

| | |
|--|------------|
| 9.3 Present State-of-the-Art and Applications | 417 |
| 9.3.1 Vacuum Interrupter Design and Technology | 417 |
| 9.3.2 Medium Voltage Circuit Breakers | 420 |
| 9.3.3 Medium Voltage Contactors | 421 |
| 9.3.4 Low Voltage Circuit Breakers | 422 |
| 9.3.5 Low Voltage Contactors | 422 |
| 9.3.6 High Voltage Vacuum Breakers | 423 |
| 9.3.7 Load Breakers | 423 |
| 9.3.8 Transformer Tap Changers | 424 |
| 9.3.9 Other Applications | 425 |
| 9.4 Future Aspects | 426 |
| References | 427 |
| 10 Vacuum Electron Sources and their Materials and Technologies | 429 |
| <i>G. Gaertner and H.W.P. Koops</i> | 429 |
| 10.1 Thermionic Vacuum Electron Sources | 429 |
| 10.1.1 Historical Development | 429 |
| 10.1.2 Fundamentals of Thermionic Emission | 431 |
| 10.1.3 Types of Thermionic Cathodes, Properties and Applications | 435 |
| 10.2 Non-Thermionic Electron Sources | 450 |
| 10.2.1 Historic Development | 450 |
| 10.2.2 Field Emission Electron Cathodes | 451 |
| 10.2.3 Thermo-field Emission Electron Cathodes | 453 |
| 10.2.4 Cold Field Electron Emission Cathodes | 454 |
| 10.2.5 Novel Cathode Materials | 456 |
| 10.2.6 Trends of Novel Developments | 457 |
| 10.2.7 Metal–Insulator–Metal (MIM) Emitter Materials | 459 |
| 10.2.8 Diamond Hopping Electron Emitters | 459 |
| 10.2.9 Carbon Nanotube Emitters | 461 |
| 10.2.10 Other Carbon Emitters and Future Development Trends | 461 |
| 10.3 Other Electron Emitters | 463 |
| 10.3.1 pn-emitters | 463 |
| 10.3.2 Secondary Emission | 466 |
| 10.3.3 Ferroelectric Electron Emission | 467 |
| 10.3.4 Photo-electron Emission | 467 |
| 10.4 Vacuum Electronic Construction | 470 |
| 10.4.1 Spacers for FEA’s | 470 |
| 10.4.2 Anodic Bonding | 470 |
| 10.4.3 Vacuum Generation in On-Chip Vacuum Electronic Devices | 472 |
| 10.5 Materials of Vacuum Electron Sources | 473 |
| References | 478 |
| 11 Vacuum Technology | 483 |
| <i>W. Knapp</i> | 483 |
| 11.1 Introduction and History | 483 |
| 11.2 Gases in Vacuum Systems | 483 |
| 11.2.1 The Fundamentals | 483 |

- 11.2.2 The Ideal Gas Law 484
- 11.2.3 The Pressure Ranges in Vacuum Technology 485
- 11.2.4 Surface Interactions and Outgassing 487
- 11.3 Vacuum Pumps 487
 - 11.3.1 Introduction 487
 - 11.3.2 Pumps for Rough and Medium Vacuum 488
 - 11.3.3 Pumps for High Vacuum (HV) and Ultrahigh Vacuum (UHV) .. 490
 - 11.3.4 Pump Selection 497
- 11.4 Vacuum Pressure Measurement 497
 - 11.4.1 Introduction 497
 - 11.4.2 Total Pressure Gauges 498
 - 11.4.3 Partial Pressure Gauges 506
- 11.5 Vacuum Materials and Components 508
 - 11.5.1 Material Properties for Vacuum Applications 508
 - 11.5.2 Component Standards and Constructions 511
 - 11.5.3 Cleaning Procedures 512
- 11.6 Leak and Leak Detection 514
 - 11.6.1 Introduction 514
 - 11.6.2 Leak Testing Methods 514
 - 11.6.3 Helium Leak Detectors 515
 - 11.6.4 Leak Testing of Vacuum Microelectronic Devices 517
- 11.7 Examples of Vacuum Systems 517
 - 11.7.1 UHV System for Field Emission Characterisation 517
 - References 519
- Index** 521

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